

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Mei Chang et al.

Serial No.: 10/634.662

Confirmation No.: 6355

Filed: August 4, 2003

For: Ruthenium Layer
Formation for Copper
Film Deposition

Group Art Unit: 1762

Examiner: Kelly M. Stouffer

MAIL STOP AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF TRANSMISSION

I hereby certify that this correspondence is being electronically transmitted to the U.S. Patent and Trademark Office via EFS-Web to the attention of Examiner Kelly M. Stouffer, on the date shown below.

April 17, 2007
Date

John-Paul F. Cherry

Dear Sir:

RESPONSE TO THE EXAMINER INTERVIEW ON APRIL 5, 2007 AND THE FINAL
OFFICE ACTION DATED JANUARY 29, 2007

In response to the Examiner Interview on April 5, 2007 and the Final Office Action dated January 29, 2007, having a shortened statutory period for response set to expire on April 29, 2007, please enter this Response and reconsider the claims pending in the application for reasons discussed below. Although the Applicant believes that no additional fees are due in connection with this Response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/005975.P1/JPC, for any fees, including extension of time fees or excess claim fees, required to make this Response timely and acceptable to the Office.

Amendments to the Claims begin on page 2 of this paper. **Remarks** begin on page 12 of this paper.